先進封裝協作型技術團隊

透過高度協作能力，讓不同體系客戶都能成功

C SUN 志聖工業

2026 Q2 Investor's meeting

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicality, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

G2C+ Alliance

Cross Holding Structure

G2C+ Alliance: The Platform Advantage

Contrel (東捷)

- Laser Application (雷射應用)
- Sputtering & Dry Etching (真空濺鍍 & 乾蝕刻)

GMM (均華)

- Die Attach (黏晶)
- Chip Sorter (揀晶)

2,400+

聯盟總人數
(Total Alliance Workforce)

900+

研發人員
(R&D Personnel)

Sun (志聖)

- Thermal (熱)
- Bonder (壓合)
- Lamination (貼膜)
- Wet Process (濕製程)
- Peeling (撕膜)
- UV/Plasma (光/電漿)

GPM (均豪)

- AOI (檢測)
- Metrology (量測)
- Grinding (研磨)
- Polishing (拋光)

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CSun - Linkou
ASE
TSMC
GPM
GMM
TSMC
TSMC
C Sun
GPM
Chiayi
TSMC
TSMC
Tainan
Contrel
GPM
GMM
ASE
Kaohsiung
ASE
快速協作網路 (Co-development Network)
建立在地零時差 (Zero-time-difference) 支援機制：就近服務大廠客戶，確保高階製程設備穩定運行與聯合開發。
ZERO-TIME DEVELOPMENT SYNC
FLEXIBIILTY
TELEMETRY
生產腹地 (Production Resilience)
整合台南南科與樹谷的萬坪廠房：為聯盟提供高度靈活的巨型自動化與組裝產線空間。
AUTOMATION
FLEXIBILTY
TELEMETRY
ROSSO CORSA

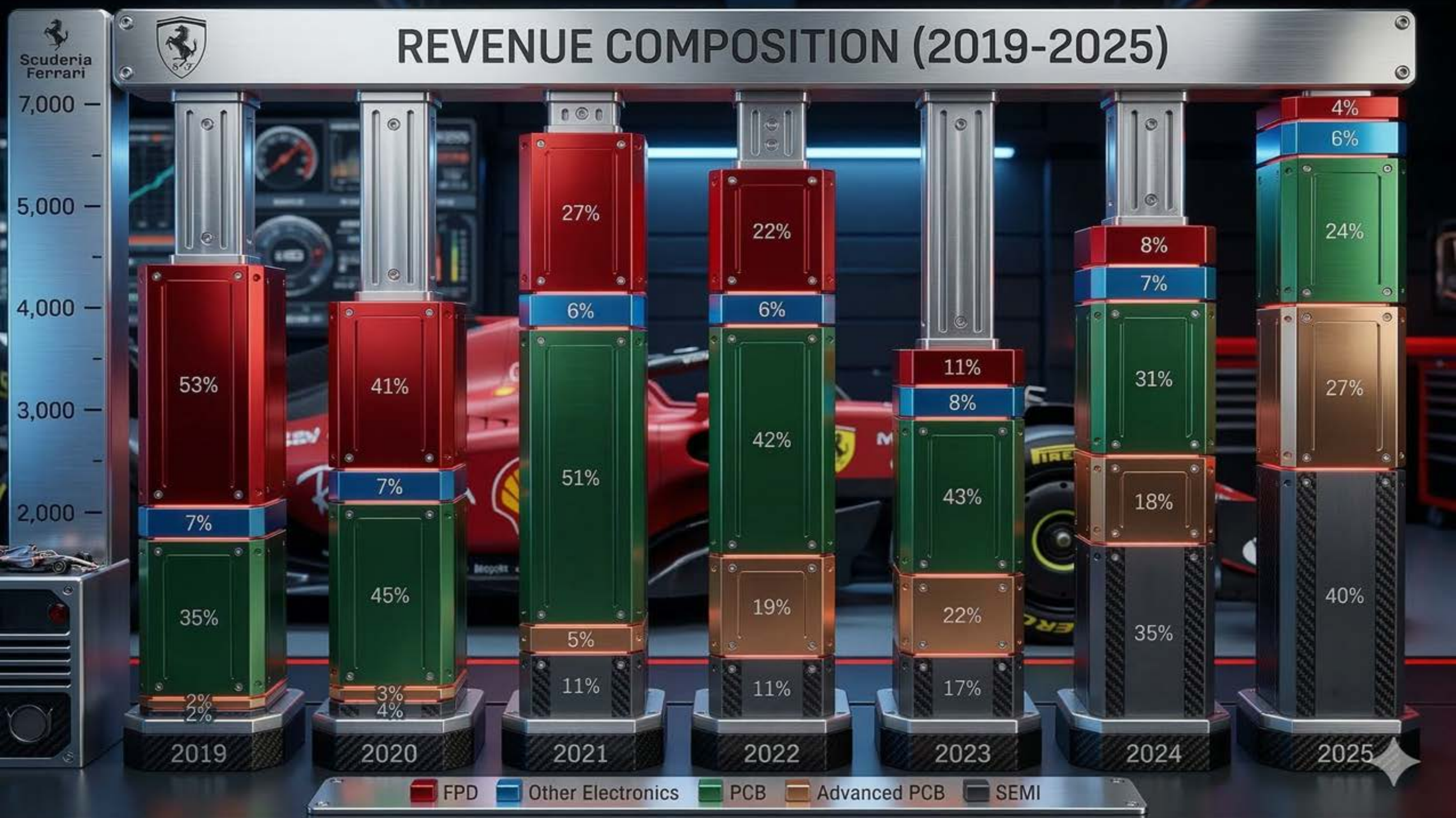
AI賽道上的專業協作團隊

連續獲得冠軍車隊肯定

2023:
Excellent Production Support
(卓越量產支援)

2024:
Outstanding Improvement
(傑出持續改善)

2025:
Excellent Production Support
(卓越量產支援)


Scuderia Ferrari
REVENUE COMPOSITION (2019-2025)
7,000
5,000
4,000
3,000
2,000
53%
7%
35%
2%
2%
41%
7%
45%
3%
4%
27%
6%
51%
5%
11%
22%
6%
42%
19%
11%
11%
8%
43%
22%
17%
8%
7%
31%
18%
35%
4%
6%
24%
27%
40%
2019
2020
2021
2022
2023
2024
2025
FPD
Other Electronics
PCB
Advanced PCB
SEMI

2025 年財務亮點：結構轉型與獲利創新高

2025 年營收

NT$ 61 億元

創歷史新高

2025 每股盈餘 (EPS)

NT$ 5.50 元

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2026 年度開局：累計營收創歷史新高

客戶的資本支出（CAPEX）持續流入，為未來成長提供永續動能。

動態應對客戶的交機排程

TSMC, intel, GF
FOUNDRY ACCESS TRACK
InFO
SoIC
EMIB
X-CUBE
WMCM
TSMC | Intel | GF
OSAT
AI substrate & HDI
AI SUBSTRATE & HDI
ACCESS TRACK
ABF
HDI
SAP
mSAP
OSAT
ACCESS TRACK
Adv. PLP
SoIC
InFO
FlipChip
FoCoS
FoPLP
CoWoS
CoWoS
CoWoP
CoWoP
CoWoS
Advanced Packaging
GRAND CIRCUIT
GRAND CIRCUIT
mSAP

C SUN & G2C+
透過策略演進驅動成長

技術藍圖：全方位製程覆蓋
Technology Roadmap: Full Spectrum Coverage

Technology Spark Matrix

Foundry
(晶圓代工)

- CoWoS
- SoIC
- WMCM
- Adv. PLP

OSAT
(封測廠)

- oS
- BSM
- CoW
- CoWoP
- EMIB
- PLP
  (Panel Level Packaging)

Advanced PCB
(先進板廠)

- IC Substrate
  (載板)
- HDI
- CoWoP

不僅掌握現有先進製程紅利，更已佈局未來 3 年 新製程需求

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研發資源配置與技術升級
R&D Resource Allocation & Tech Upgrade

先進封裝產業鏈新世代製程與設備升級
Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain

技術升級期的投入將支持未來3-5年成長動能

築巢引鳳：研發中心與全球擴張

18.2 億 NTD

打造研發中心，為多元
前瞻設備開發奠定基礎。

USA

Japan

台中水湳研發中心
(Taichung Shuinan R&D Center)
The Innovation Hub

精科二廠
(Jingke Plant 2)
Capacity Expansion

14.8 億 NTD

購置廠房與設施，
確保未來產能無虞。

F1先進封裝大賽
Foundry主賽道
CoWoS / SoIC / WMCM
晶圓先
tsmc
OSAT賽道
PLP / oS / Bumping / CoW / EMIB
ASE
PTI
AI載板多層板賽道
IC Substrate / HDI
Unimicron
Zhen Ding